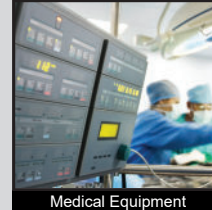
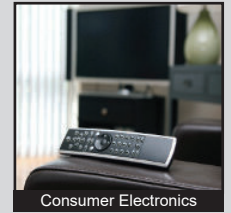
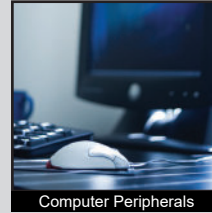
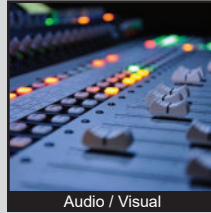


RT3301 SERIES TACT SWITCH

APPLICATIONS / MARKETS



RoHS

SPECIFICATIONS

Electrical Rating: 50mA, 12VDC
Contact Resistance: 100mΩ Max. (Initial)
Insulation Resistance: 100MΩ Min. at 100VDC
Dielectric Strength: 250VAC for 1 Minute
Life Cycles: 100,000 cycles
Operating Temperature: -40°C to 85°C
Travel: 0.25mm +0.2mm / - 0.1mm
Contact Material: Silver
Operating Force: 100gf ± 30gf
 160gf ± 50gf
 260gf ± 50gf
 320gf ± 70gf
Function: SPST, Off-(On)
Packaging: Tape and Reel, 1,000 pcs/reel

FEATURES & BENEFITS

- Top actuated, reverse surface mount design
- 6.00 x 6.00mm size
- Multiple actuation force options
- Up to 100,000 cycle life expectancy
- Tape and Reel packaging

PART NUMBER CONFIGURATOR

Series <input type="text" value="R"/> <input type="text" value="T"/> <input type="text" value="3"/> <input type="text" value="3"/> <input type="text" value="0"/> <input type="text" value="1"/> RT3301	Actuator Height <input type="text" value="A"/> A - 5.3mm	Actuation Force <input type="text" value="F"/> <input type="text" value="1"/> <input type="text" value="0"/> <input type="text" value="0"/> F100 - 100gf F160 - 160gf F260 - 260gf F320 - 320gf	Contact Plating <input type="text" value="Q"/> Q - Silver
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Specifications subject to change without notice 3.28.2024



E-SWITCH®

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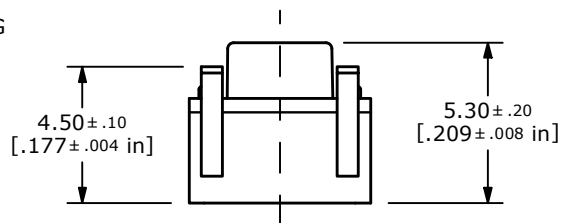
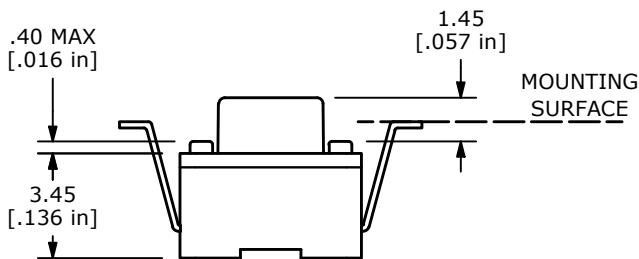
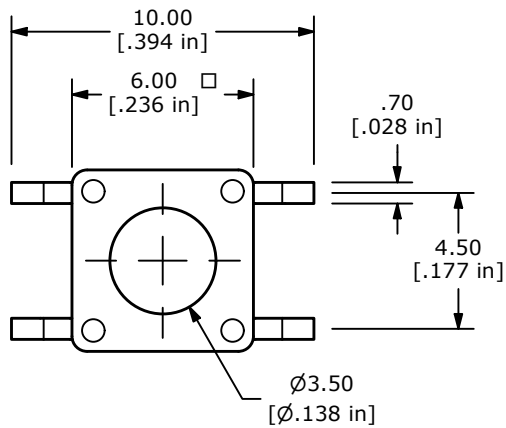
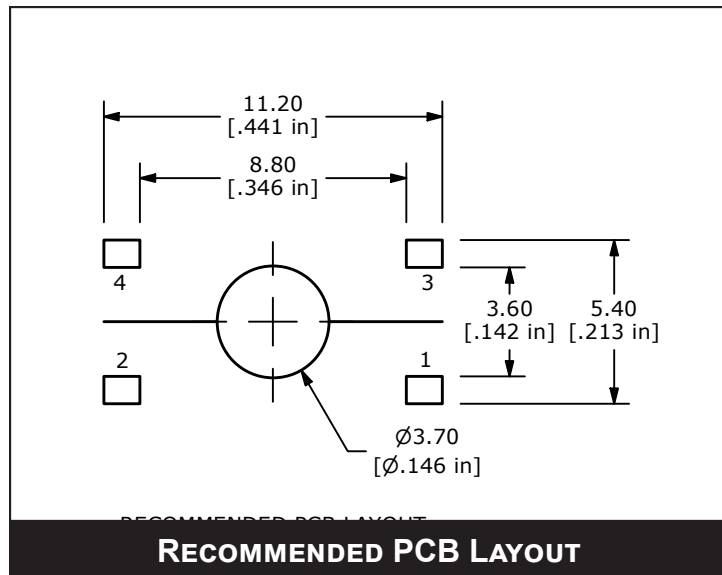
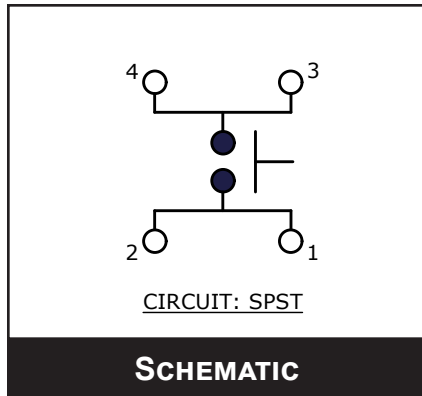
800.867.2717

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ANTI-VANDAL SWITCHES
DETECTOR SWITCHES
DIP SWITCHES
KEYLOCK SWITCHES
NAVIGATION SWITCHES
PUSHBUTTON SWITCHES
ROCKER SWITCHES
ROTARY SWITCHES
SLIDE SWITCHES
SNAP ACTION SWITCHES
TACTILE SWITCHES
TOGGLE SWITCHES
CAP OPTIONS

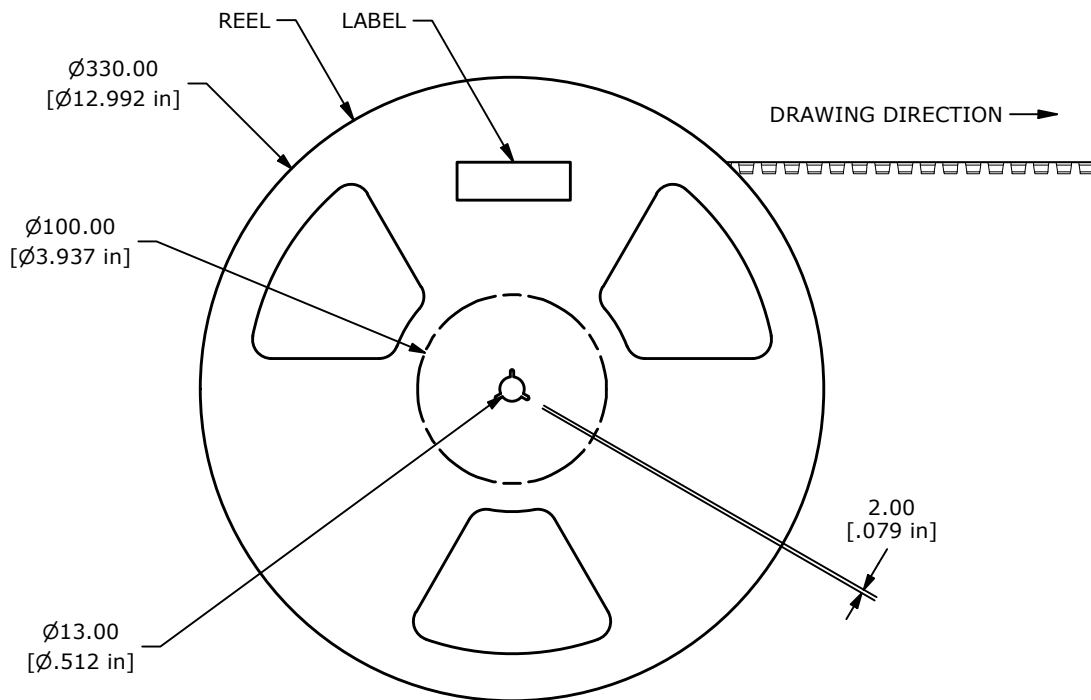
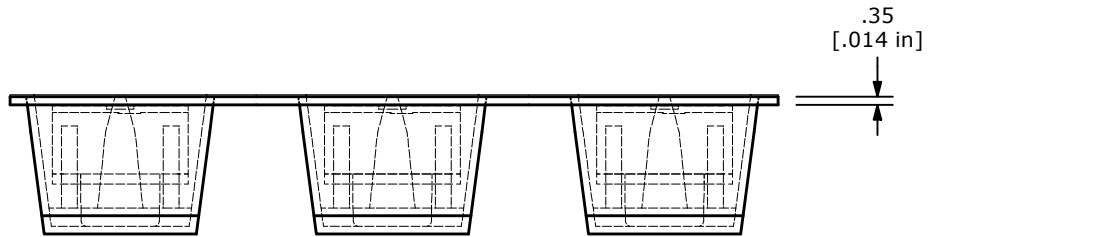
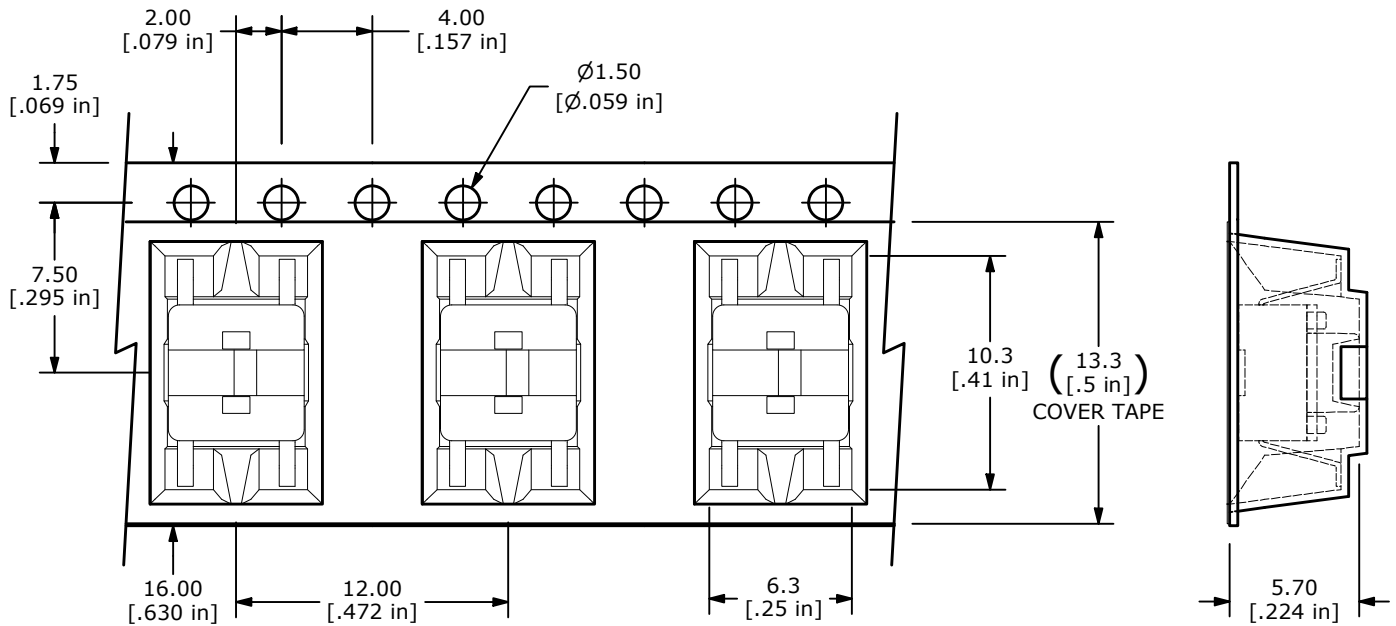
RT3301 SERIES TACT SWITCH

BODY DIMENSIONS



RT3301 SERIES TACT SWITCH

BODY DIMENSIONS TAPE AND REEL



RECOMMENDED SOLDER PROCESS

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

“TYPICAL” SMT REFLOW (Pb and Pb-Free)

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3 °C/second max.	3 °C/second max.
Preheat -Temperature Min ($T_{s_{min}}$) -Temperature Max ($T_{s_{max}}$) -Time ($t_{s_{min}}$ to $t_{s_{max}}$)	100 °C 150 °C 60-120 seconds	150 °C 200 °C 60-180 seconds
Time Maintained above: -Temperature (T_L) -Time (t_L)	183 °C 60-150 seconds	217 °C 60-150 seconds
Time within 5 °C of actual Peak Temperature (t_p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package surface.

